

- ★ Super Low Gate Charge
- ★ Green Device Available
- ★ Excellent Cdv/dt effect decline
- ★ Advanced high cell density Trench technology

Product Summary



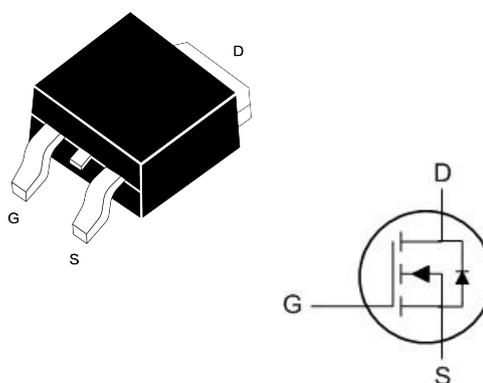
BVDSS	RDSON	ID
100V	20 mΩ	40A

Description

The JHS40N10 is the highest performance trench N-ch MOSFETs with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The JHS40N10 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

TO-252 Pin Configuration



Absolute Maximum Ratings $T_C=25^{\circ}\text{C}$ unless otherwise specified

Symbol	Parameter	Max.	Units
V_{DSS}	Drain-Source Voltage	100	V
V_{GSS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current ^{note5}	$T_C = 25^{\circ}\text{C}$ 40	A
I_D	Continuous Drain Current ^{note5}	$T_C = 100^{\circ}\text{C}$ 16	A
I_{DM}	Pulsed Drain Current ^{note3}	100	A
P_D	Power Dissipation ^{note2}	$T_C = 25^{\circ}\text{C}$ 27	W
I_{AS}	Avalanche Current ^{note3,6}	8	A
E_{AS}	Single Pulse Avalanche Energy ^{note3,6}	16	mJ
$R_{\theta JC}$	Thermal Resistance, Junction to Case	4.65	$^{\circ}\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient ^{note1,4}	62	$^{\circ}\text{C}/\text{W}$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150	$^{\circ}\text{C}$

Electrical Characteristics $T_C=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	100	-	-	V
I_{DSS}	Drain-Source Leakage Current	$V_{DS} = 80V, V_{GS} = 0V$	-	-	1	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	± 100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.2	1.8	2.6	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 10V, I_D = 15A$	-	20	23	m Ω
		$V_{GS} = 4.5V, I_D = 10A$	-	-	33	m Ω
g_{fs}	Forward Threshold Voltage	$V_{DS} = 10V, I_D = 20A$	-	22	-	S
R_g	Gate Resistance	$V_{DS} = V_{GS} = 0V, f = 1.0MHz$	-	1.62	-	Ω
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS} = 50V, V_{GS} = 0V,$ $f = 1.0MHz$	-	822	-	pF
C_{oss}	Output Capacitance		-	310	-	pF
C_{rss}	Reverse Transfer Capacitance		-	23.5	-	pF
Switching Characteristics						
Q_g	Total Gate Charge	$V_{DS} = 50V, I_D = 20A,$ $V_{GS} = 10V$	-	22.7	-	nC
Q_{gs}	Gate-Source Charge		-	6.2	-	
Q_{gd}	Gate-Drain("Miller") Charge		-	5.3	-	
$t_{d(on)}$	Turn-On Delay Time	$V_{DS} = 50V, I_D = 20A,$ $R_G = 3\Omega, V_{GS} = 10V$	-	15	-	ns
t_r	Turn-On Rise Time		-	3.2	-	
$t_{d(off)}$	Turn-Off Delay Time		-	30	-	
t_f	Turn-Off Fall Time		-	7.6	-	
Diode Characteristics						
I_S	Continuous Source Current		-	-	40	A
V_{SD}	Diode Forward Voltage	$I_S = 20A, V_{GS} = 0V$	-	0.88	1.0	V
t_{rr}	Reverse Recovery Time	$I_{SD} = 20A,$ $di_{SD}/dt = 100A/\mu s$	-	45	-	ns
Q_{rr}	Reverse Recovery Charge		-	59	-	nC

Notes:

1. The value of $R_{\theta JC}$ is measured in a still air environment with $T_A = 25^\circ\text{C}$ and the maximum allowed junction temperature of 150°C . The value in any given application depends on the user's specific board design.
2. The power dissipation P_D is based on $T_{J(MAX)} = 150^\circ\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
3. Single pulse width limited by junction temperature $T_{J(MAX)} = 150^\circ\text{C}$.
4. The $R_{\theta JA}$ is the sum of the thermal impedance from junction to case $R_{\theta JC}$ and case to ambient.
5. The maximum current rating is package limited.
6. The EAS data shows Max. rating. The test condition is $V_{DS} = 50V, V_{GS} = 10V, L = 0.5mH$

Typical Performance Characteristics

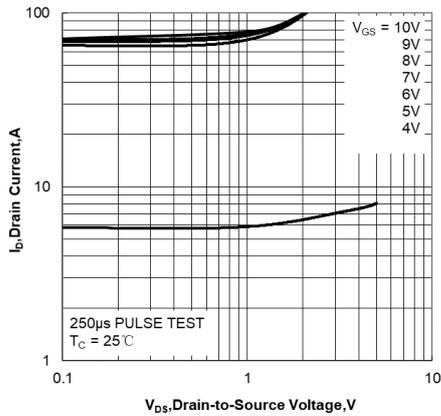


Figure 1. Output Characteristics

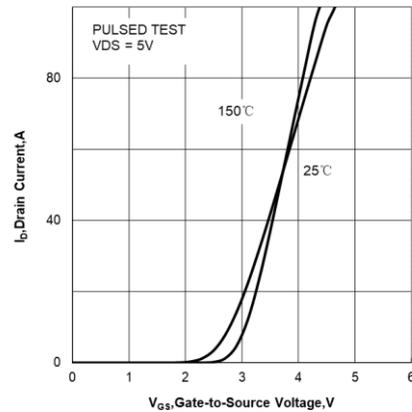


Figure 2. Transfer Characteristics

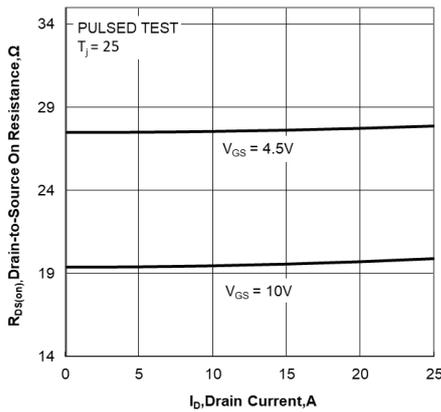


Figure 3. Drain-to-Source On Resistance vs Drain Current

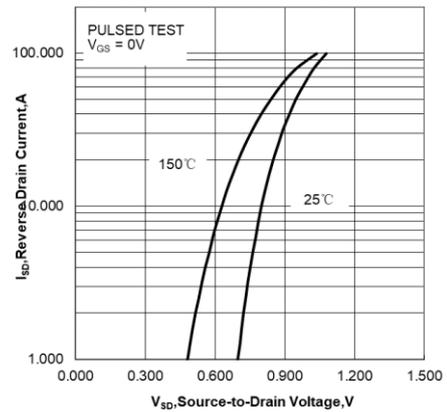


Figure 4. Body Diode Forward Voltage vs Source Current and Temperature

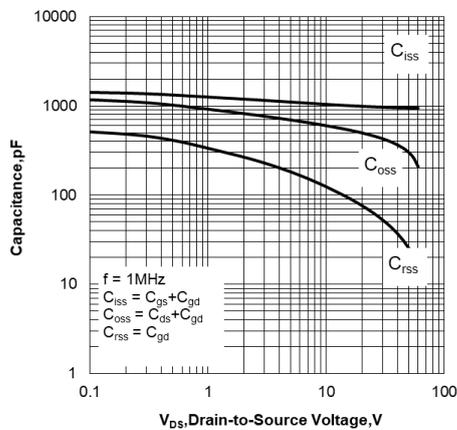


Figure 5. Capacitance Characteristics

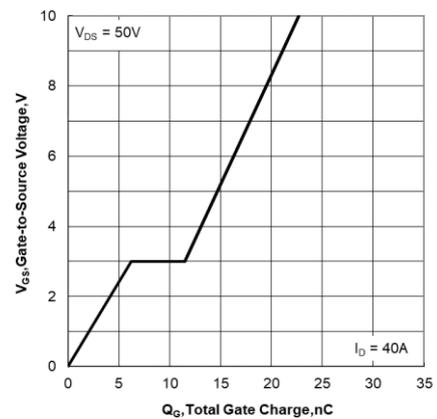


Figure 6. Gate Charge Characteristics

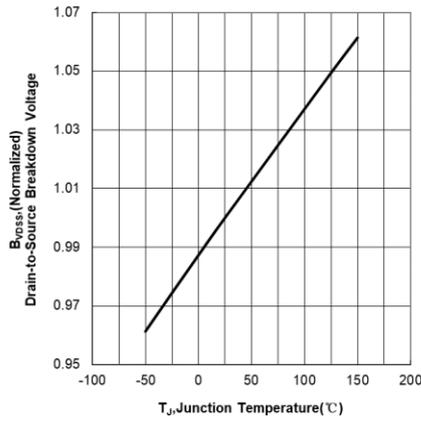


Figure 7. Normalized Breakdown Voltage vs Junction Temperature

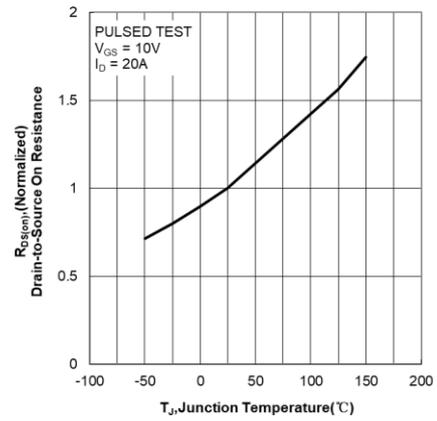


Figure 8. Normalized On Resistance vs Junction Temperature

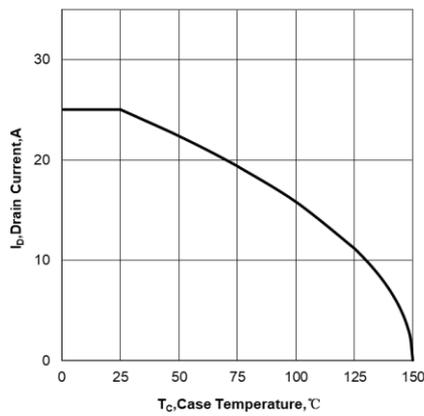


Figure 9. Maximum Continuous Drain Current vs Case Temperature

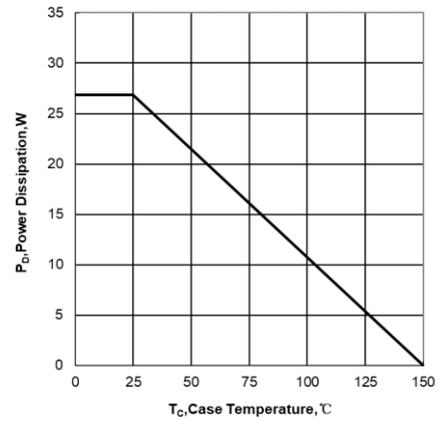


Figure 10. Maximum Power Dissipation vs Case Temperature

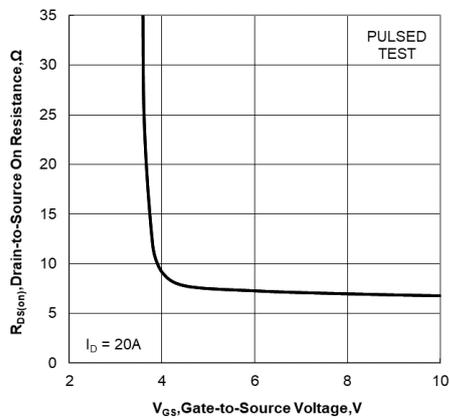


Figure 11. Drain-to-Source On Resistance vs Gate

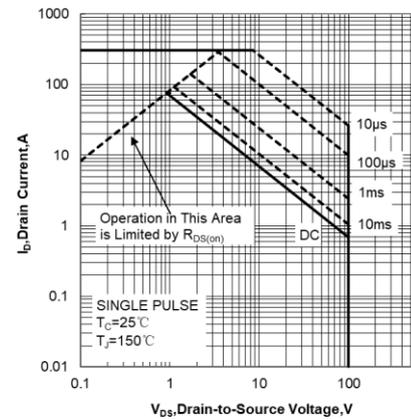


Figure 12. Maximum Safe Operating Area

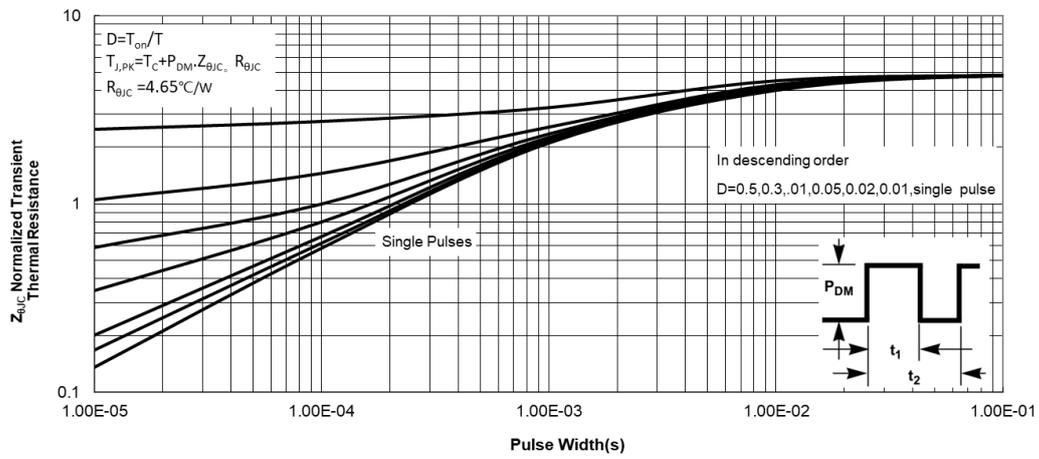
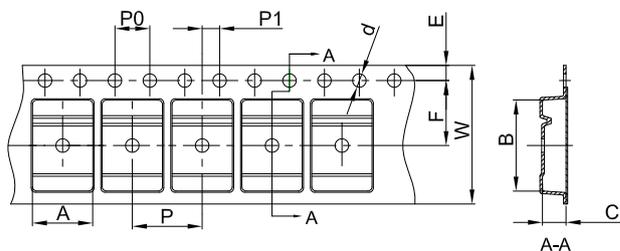


Figure 13. Maximum Effective Transient Thermal Impedance, Junction-to-Case

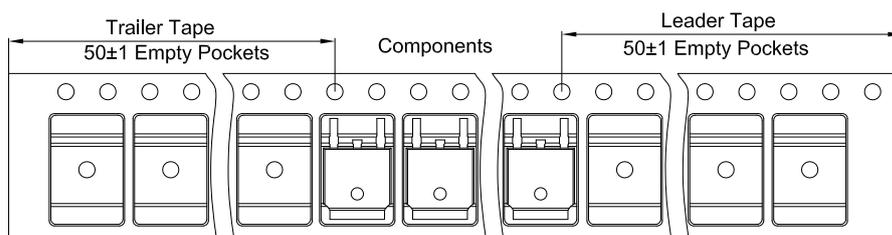
TO-252-2L Tape and Reel

TO-252 Embossed Carrier Tape

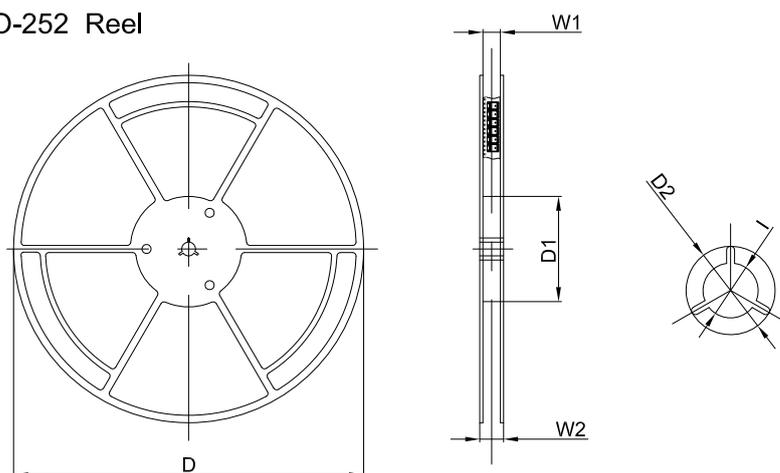


Dimensions are in millimeter										
Pkg type	A	B	C	d	E	F	P0	P	P1	W
TO-252	6.90	10.50	2.70	Ø1.55	1.75	7.50	4.00	8.00	2.00	16.00

TO-252 Tape Leader and Trailer

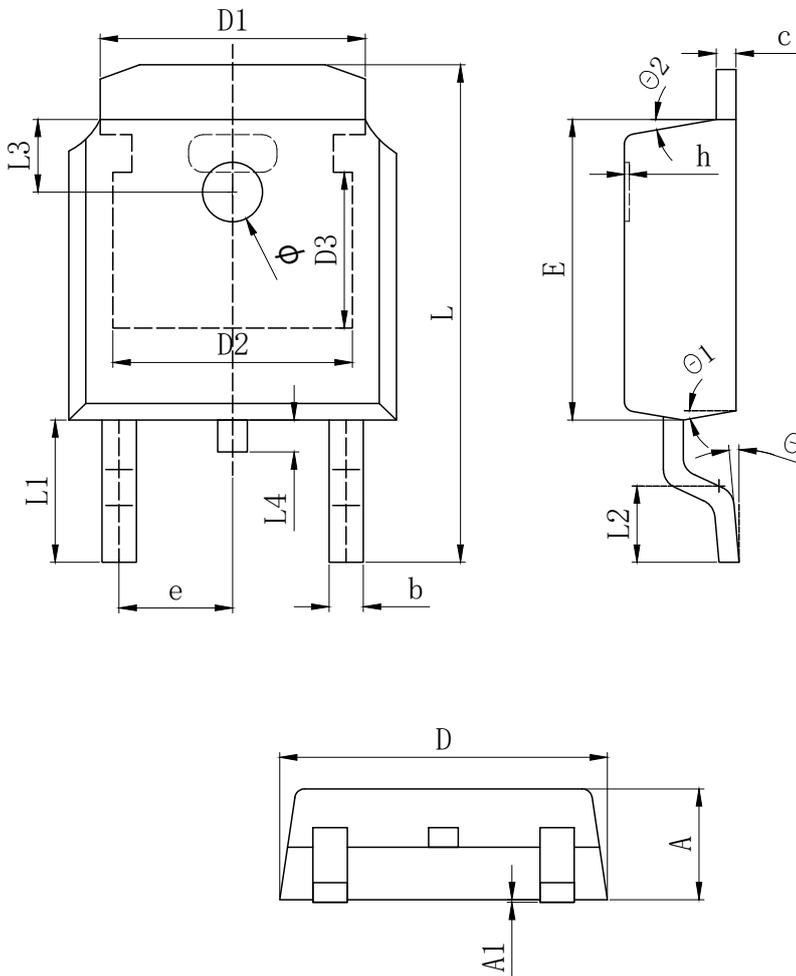


TO-252 Reel



Dimensions are in millimeter						
Reel Option	D	D1	D2	W1	W2	I
13"Dia	330.00	100.00	Ø21.00	16.40	21.00	Ø13.00

REEL	Reel Size	Box	Box Size(mm)	Carton	Carton Size(mm)	G.W.(kg)
2,500 pcs	13inch	2,500 pcs	340×336×29	25,000 pcs	353×346×365	



SYMBOL	MILLIMETER		
	MIN	Typ.	MAX
A	2.200	2.300	2.400
A1	0.000		0.127
b	0.640	0.690	0.740
c (电镀后)	0.460	0.520	0.580
D	6.500	6.600	6.700
D1	5.334 REF		
D2	4.826 REF		
D3	3.166 REF		
E	6.000	6.100	6.200
e	2.286 TYP		
h	0.000	0.100	0.200
L	9.900	10.100	10.300
L1	2.888 REF		
L2	1.400	1.550	1.700
L3	1.600 REF		
L4	0.600	0.800	1.000
ϕ	1.100	1.200	1.300
θ	0°		8°
θ_1	9° TYP		
θ_2	9° TYP		

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